

TECHNICAL SPEC FOR Vertical furnace

System Model:	3200 TEL Alpha 8 series
Specific model:	Model VCF
Process (Poly, TEOS, Nitride, Pyro, etc.):	NITRIDE process
APCVD or LPCVD:	LPCVD
HDD and SW included or not:	SW installed, tool version without HDD
Main controller type:	3200
SiC/quartz included or not:	Separated
Substrate size:	6 inch
SMIF:	No
Gas config:	For nitride process, 3200
Leak detection:	No
Wafer notch aligner:	6" Jeida flat
Handler type:	TBAWL
Indexer:	With wafer counter for 6"
Carrier type, FOUP:	6" black carriers, No FOUP
Buffer Capacity:	6 prod carriers, and 2 carriers for mon, extraDummies, dummies
Boat type:	170 slots, 150 prod wafers
Boat rotation:	Yes
Heater type:	5Zone
Carrier ID reader:	No

MFC: 3X N₂ and 1X NH₃, 1X SiH₂Cl₂

Pressure transducer: 1X 1Torr, 1X 1000Torr

CKD-VEC Vacuum pressure controller: FCV controller

CDA: Yes

Temperature controller: M-120

Exhaust controller: Yes

Power Box: No

Missing parts: No

Defected parts: No

Operating system: 3200

Serial plate

NITRIDE4

TYPE	VCR		
SERIAL NO.	FL20029		
POWER AC	480 V	31.1 kVA	
PHASE			
TYPE OF DISTRIBUTION	WIRE		
FREQUENCY	50/60Hz		
MAXIMUM RATED CURRENT	A		
TUBE	-25-007	HEATER	
DATE OF MANUFACTURE			

TOKYO ELECTRON LIMITED